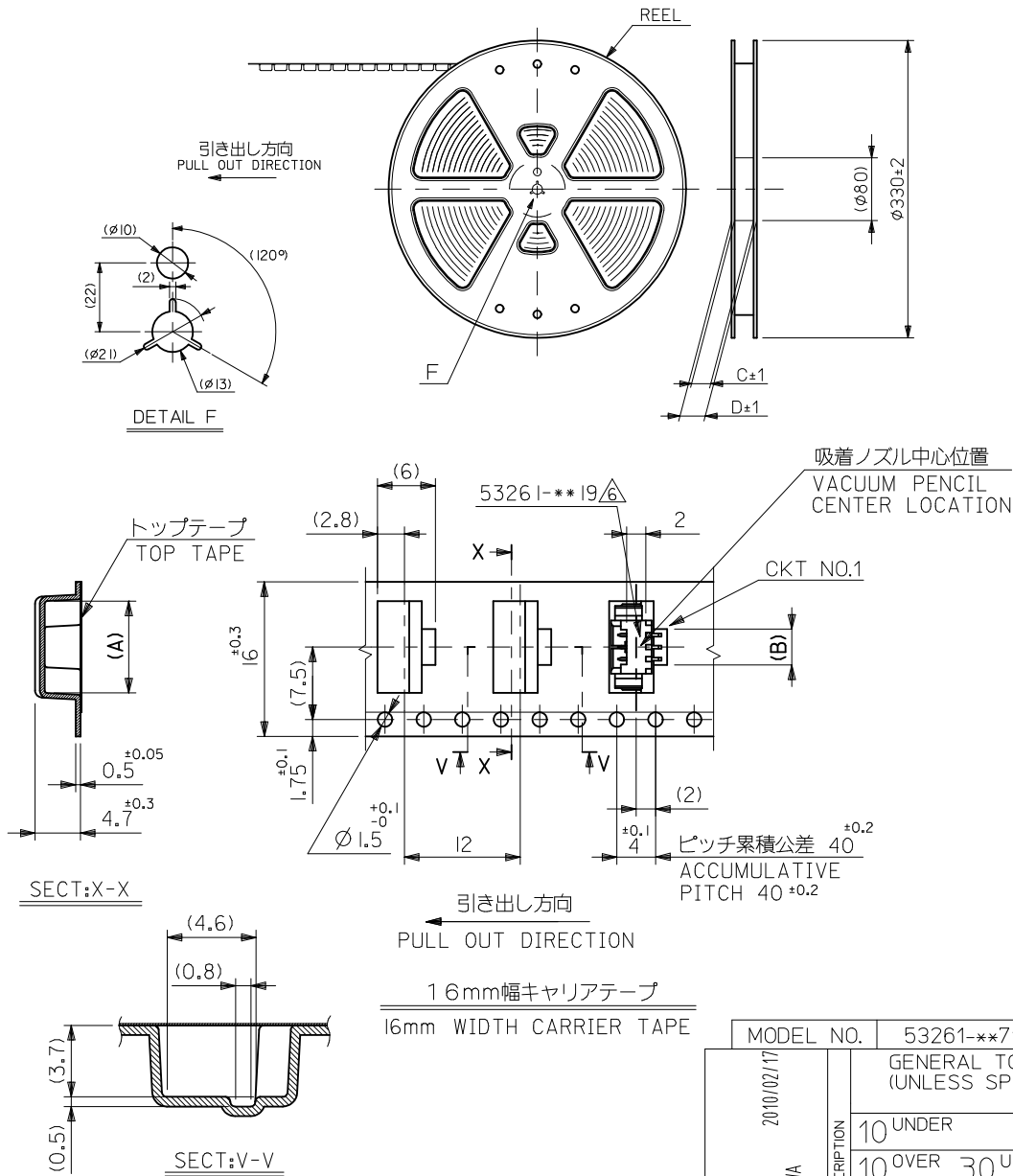


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30					
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART			SD-51021-002		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

10 9 8 7 6 5 4 3 2 1

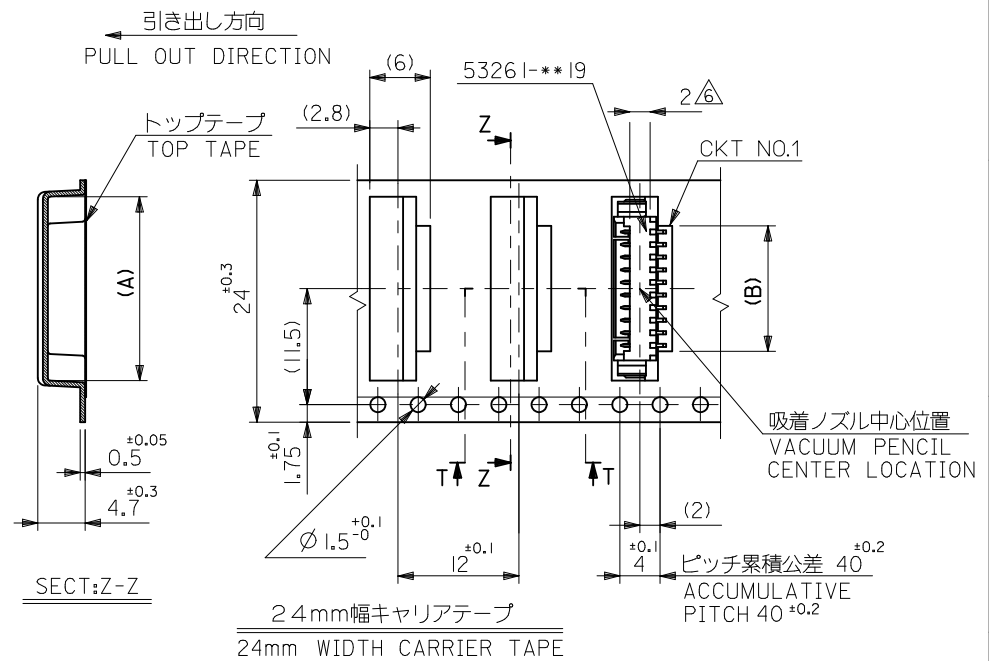
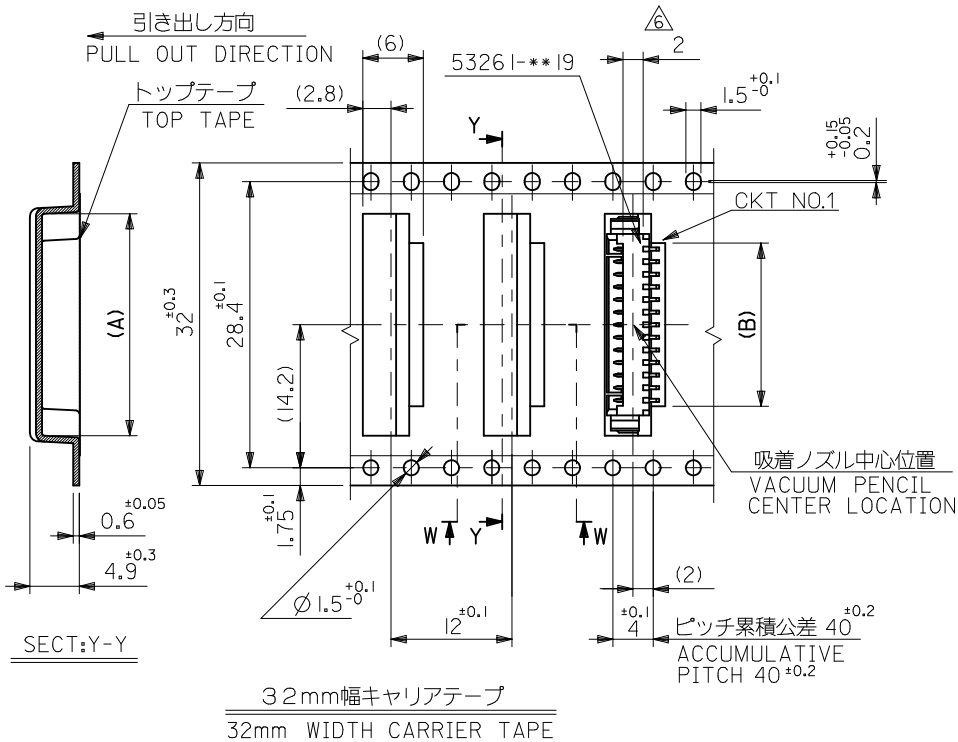


注記 NOTES



- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS,SEE SD-53261-024
- 梱包数量：1000個/リール
NUMBER OF CONNECTOR:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダー部 TOP TAPE LEADER PART 175⁺²⁵
トップテープ未接着部 TOP TAPE NON-BONDED PART 25⁺⁵

4. 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)
トップテープ (TOP TAPE): PET ,PE ,PEF
リール (REEL):ポリスチレン (PS) <リサイクル材含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
- コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA
- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16		21.4	17.4	3.7 2.45	9.5 8.25	53261-0371 53261-0271	3 2
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.
DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
DRAWN BY H.SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
CHECKED BY K.TOJO		DATE '04/02/06					
APPROVED BY NUKITA		DATE 2010/02/18					
MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
SEE TABLE & SHEET 2,3		SD-53261-023				1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
24	29.4	25.4	6.2	12	-0571	5
			4.95	10.75	53261-0471	4
					EMBOSSD TAPE PACKAGE	種数
					オーダー番号 ORDER NO.	CKT.
					DESIGN UNITS	
					METRIC	
					THIRD ANGLE	
					PROJECTION	

MODEL NO.		53261-**71		CARRIER TAPE WIDTH		D		C		B		A		オーダー番号 ORDER NO.		CKT.	
REVISED EC NO: DRWN:YGO10 CHKD:KASAKAWA APPR: REV	DESCRIPTION 2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE MM ONLY				SCALE ---		DESIGN UNITS METRIC		 THIRD ANGLE PROJECTION			
		10 UNDER		± 0.2		DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG							
		10 OVER 30 UNDER		± 0.25		CHECKED BY K. TOJO		DATE '04/02/06									
		30 OVER		± 0.3		APPROVED BY NUKITA		DATE 2010/02/18									
		ANGULAR ±3 °		MATERIAL NO.				 MOLEX INCORPORATED				SHEET NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE & SHEET 13				DOCUMENT NO. SD-53261-023				2 OF 3			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

E

D

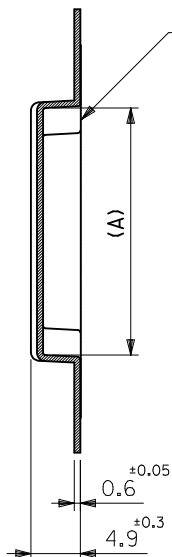
C

B

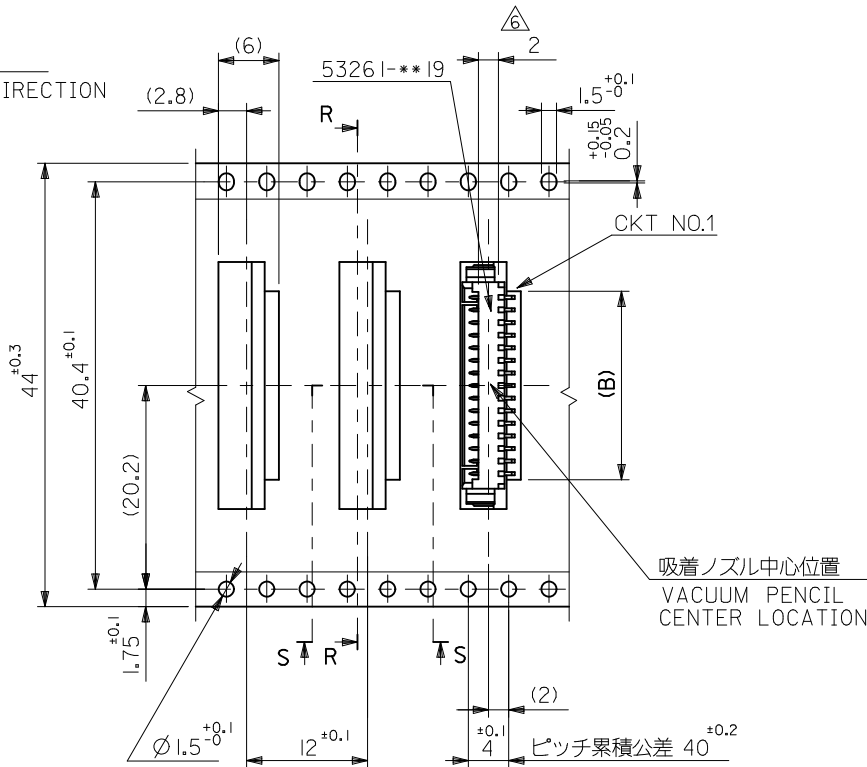
A

引き出し方向
PULL OUT DIRECTION

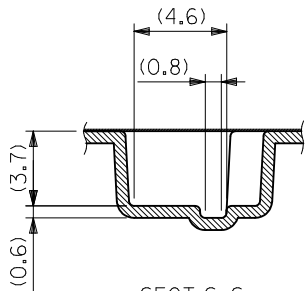
トップテープ
TOP TAPE



SECT:R-R

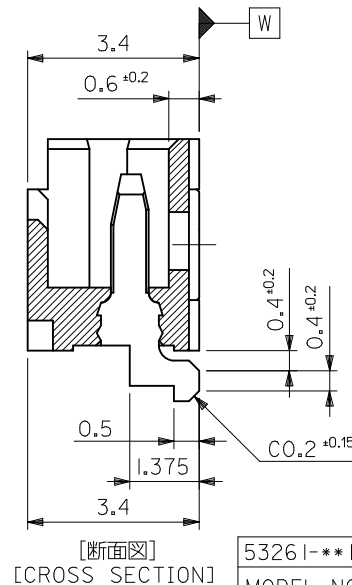
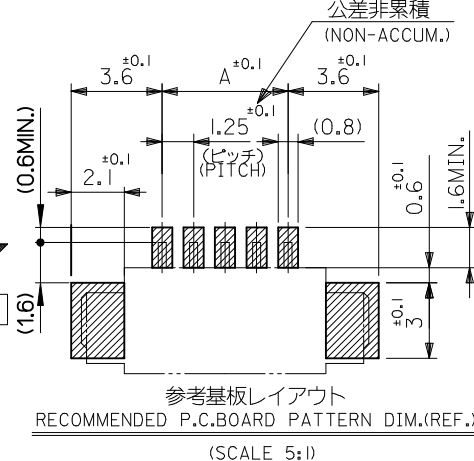
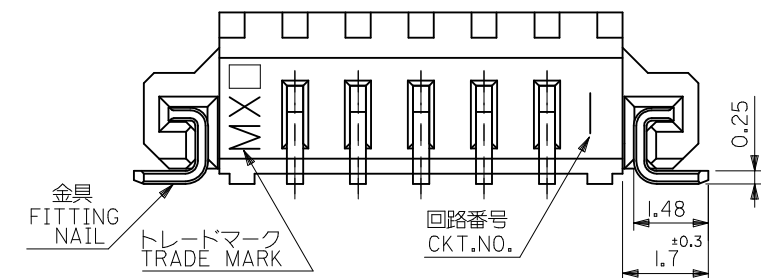
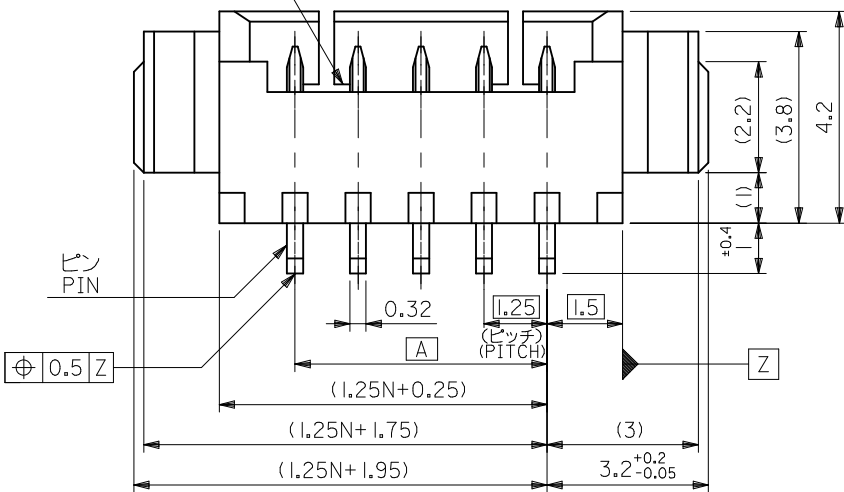
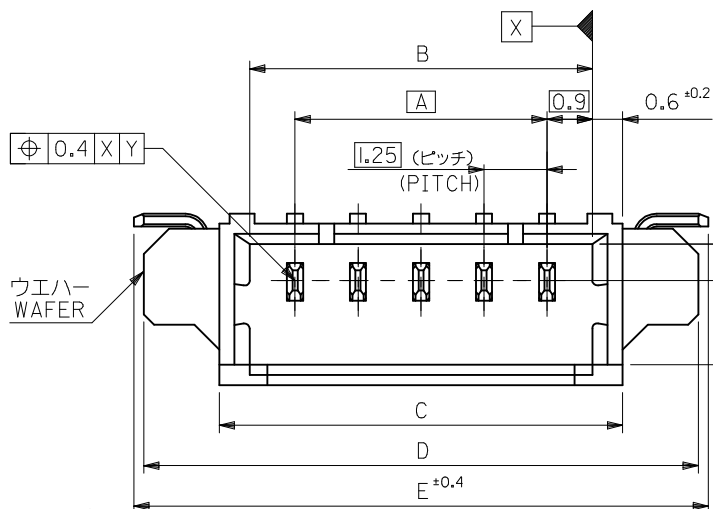


44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT:S-S

44		49.4	45.4	18.7	24.5	53261-1571	I5
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	53261-1471	I4
MODEL NO. 53261-***71		D		C	B	A	EMBOSSED TAPE PACKAGE 極数
REVISED		DESCRIPTION		DIMENSION STYLE		SCALE	
EC NO. 2010/02/17		GENERAL TOLERANCES (UNLESS SPECIFIED)		MM ONLY		---	
DRWN: YGOTO		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	
CHKD: KASAKAWA		10 OVER 30 UNDER	± 0.25	H. SHIMABUKUR	'04/02/06	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	
APPR:		30 OVER	± 0.3	CHECKED BY	DATE	ORDER NO.	
REV		ANGULAR	± 3 °	K. TOJO	'04/02/06	MATERIAL NO.	
D		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	DOCUMENT NO.	
				NUKITA	2010/02/18	SHEET NO.	
				SEE TABLE & SHEET 12		SD-53261-023	
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



注記 NOTES

1. 嵌合相手: 51021 シリズ
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
金具: リン青銅
FITTING NAIL: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
3. ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソリダーテール部のスレ量及び金具(補強板)のスレ量は基準面 W に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-**-10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-10
6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.
7. ソルダーテール及び金具の平坦度は 0.1 以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

	26.4	26	23	21.8	20	53261-1771	53261-1719	17
	23.9	23.5	20.5	19.3	17.5	-1571	-1519	15
	22.65	22.25	19.25	18.05	16.25	-1471	-1419	14
	21.4	21	18	16.8	15	-1371	-1319	13
	20.15	19.75	16.75	15.55	13.75	-1271	-1219	12
	18.9	18.5	15.5	14.3	12.5	-1171	-1119	11
	17.65	17.25	14.25	13.05	11.25	-1071	-1019	10
	16.4	16	13	11.8	10	-0971	-0919	9
	15.15	14.75	11.75	10.55	8.75	-0871	-0819	8
	13.9	13.5	10.5	9.3	7.5	-0771	-0719	7
	12.65	12.25	9.25	8.05	6.25	-0671	-0619	6
	11.4	11	8	6.8	5	-0571	-0519	5
	10.15	9.75	6.75	5.55	3.75	-0471	-0419	4
	8.9	8.5	5.5	4.3	2.5	-0371	-0319	3
9	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2
D.	E	D	C	B	A	EMBOSSED TAPE PKG ORDER No.	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2016-1122 DRWN: QHE31 CHKD: SAKIYAMA APPR: KANEKO	DESCRIPTION J	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT				
		0.25 OVER	0.5 UNDER	± 0.05	HSHIMABU	04/02/06					
		0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE					
		1.0 OVER	10 UNDER	± 0.2	KTOJO	04/02/06	molex				
		10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE					
		30 OVER		± 0.3	MSASAO	04/02/06					
		ANGULAR ±3 °			MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
					SEE CHART		SD-53261-024		1 OF 1		
		REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

1.25 WIRE TO BOARD
WAFER ASS FOR SMT

molex

SD-53261-024

1 OF 1